



materials



an Open Access Journal by MDPI

Advances of Semiconductor Nanostructures

Guest Editor:

Message from the Guest Editor

Prof. Dr. Anna Vilà

Department of Electronic and
Biomedical Engineering,
University of Barcelona, 08028
Barcelona, Spain

Deadline for manuscript
submissions:

closed (30 June 2020)

Since gate-all-around nanowire devices were combined with 3D integration, semiconductor nanostructures have promise to scale up the overall performance of electronics technology. Traditional scaling-down has allowed the construction of components and final chips with higher speed and density, lower power, increased functionality, etc. However, a change paradigm suggests that “More Moore” and “More Than Moore” will evolve towards novel strategies involving new materials, advanced devices, or higher-value nanosystems.

This Special Issue of *Materials* attempts to cover the recent advances in semiconductor nanostructures for logic and memory, sensors and actuators, biological and mechanical nanosystems, etc.



mdpi.com/si/25147

Special issue



an Open Access Journal by MDPI

Editor-in-Chief

Prof. Dr. Maryam Tabrizian

1. Department of Biomedical Engineering, Faculty of Medicine and Health Sciences, McGill University, Montreal, QC H3A 2B6, Canada

2. Faculty of Dentistry and Oral Health Sciences, McGill University, 3640 Rue University, Montreal, QC H3A 0C7, Canada

Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

Author Benefits

Open Access: free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility: indexed within Scopus, SCIE (Web of Science), PubMed, PMC, Ei Compendex, CaPlus / SciFinder, Inspec, Astrophysics Data System, and other databases.

Journal Rank: JCR - Q1 (Metallurgy and Metallurgical Engineering) / CiteScore - Q2 (*Condensed Matter Physics*)

Contact Us

Materials Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland

Tel: +41 61 683 77 34
www.mdpi.com

mdpi.com/journal/materials
materials@mdpi.com
[X@Materials_Mdpi](https://twitter.com/Materials_Mdpi)